

-24-

ABSTRACT OF THE DISCLOSURE

An efficient substrate fabrication method is disclosed. A method of fabricating a substrate having a via terminal includes the steps of: forming a concave part on a front surface of a source substrate; forming a front surface side conductive part by filling the concave part with a conductor; forming the core substrate by back-grinding up to a position immediately before the front surface side conductive part is exposed such that a tip of the front surface side conductive part is covered with a portion of the core substrate; exposing the tip of the front surface side conductive part by forming a concave part in a rear surface of the core substrate; forming a rear surface side conductive part by filling the concave part with a conductor; and electrically and mechanically connecting the front surface side conductive part with the rear surface side conductive part.